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EV318282163

#161A

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 10/004,172 ✓  
Filing Date ..... October 9, 2001  
Inventor ..... Warren M. Farnworth et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 3729  
Examiner ..... A.D. Tugbang  
Attorney's Docket No. .... MI22-1839  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding  
Frames

*[Handwritten signature]* 10/01/03

**RESPONSE TO JUNE 4, 2003 OFFICE ACTION**

To: Mail Stop Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

From: D. Brent Kenady  
Tel. 509-624-4276; Fax 509-838-3424  
Wells St. John P.S.  
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Spokane, WA 99201-3828

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Responsive to the Office Action dated June 4, 2003, Applicant amends and  
remarks as follows:

**AMENDMENTS**

Underlines indicate insertions and ~~strikeouts~~ indicate deletions.